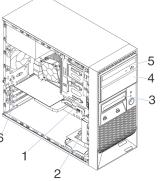
## ThinkServer TS150 Platform Specifications

Components	Specification					C
Dimensions	Tower or 4U rack.	4.70 ()	75 (0.00:)	al a makla . 404	(40.07:-)	
Weight	Height: 375 mm (14.76 in), width: 175 mm (6.89 in), depth: 431 mm (16.97 in)  Maximum configuration: 27.6 lb (12.5kg)					
vveignit	Up to one Intel X	anon. 27.0 m (12.	.oky) Core is Pentiu	m or Celeron f	amily	—— G
	processor.	5011 L3-1200 V3,	Core is, Ferrila	iii, oi celeioii i	arriny	
	Xeon E3-1280 v5  4C/3.7GHz/8MB/80W/DDR4-2133					
	Xeon E3-1280 V5 4					H
	Xeon E3-1240 v5					F
	Xeon E3-1230 v5					
	Xeon E3-1220 v5					F
	Xeon E3-1275 v5					-
	Xeon E3-1245 v5	C/3.5GHz/8MB/80V	V/DDR4-2133			N
	Xeon E3-1225 v5					
Processor		2C/3.9GHz/4MB/51V				E
FIOCESSOI		2C/3.8GHz/4MB/51V				s
		2C/3.3GHz/4MB/35V				"
		2C/3.7GHz/3MB/51V 2C/3.2GHz/3MB/35V				L
		C/3.6GHz/3MB/51V				
		2C/3.5GHz/3MB/51V				
		2C/3GHz/3MB/35W/				
		C/3.3GHz/3MB/54V				
	Pentium G4400T 2	C/2.9GHz/3MB/35V	V/DDR4-2133			
		C/2.9GHz/2MB/51V				
		2C/2.8GHz/2MB/51V				
		2C/2.6GHz/2MB/35V				
Chipset	Intel C236 Platfori					
Memory DIMMs	4 DIMM sockets w	rith 2 channels, 2	DIMMs per cha	nnel. <b>UDIMM</b> . D	DR4-2133	
Memory capacity	64GB (16GB x 4)					
Memory protection	ECC					
RAID controller	RAID controller Onboard RAID121i		0/1/5/10	AID support		6
	RAID520i PCIe 12Gbs SAS/SATA 0/1/10, 5 with optional key					
Disk bays	Supports up to four 3.5" or hybrid 3.5" + 2.5" disk drives , or up to five 2.5" disk drives. one 9.5mm optical (see right). Non-hot swap. Cables are connected to onboard SATA connectors or PCIe RAID controller. Supports one optional internal USB RDX Tape drive					
	3.5" HDD, 7.2K SAT		/2TR/3TR/4TR/5TF	R/6TR		C
Supporting storage				5,015		ĬĔ
	2.5" SSD, SATA6Gb		GB/480GB/600GB	/800GB/960GB		li
SD module	Optional. Up to 2 SDHC flash cards via SD module, 8GB each					
Optical drive	Up to two half-height optical drives or one 9.5mm optical. DVD-ROM or DVD±RW					
Network	One Gigabit Ethernet port, Intel i219LM. Supports optional discrete network					
interfaces	adapters via PCIe slots					
Security features	Power-on and administrator password. TPM (TCG 1.2-compliant)			— В		
	UEFI, system LED	s, EasyStartup, E	EasyUpdate, Por	wer Planner, and	d Diagnostic	S.
Systems	Intel Active Manag	gement Technolog	y 11 on models	with Xeon proc	essors. Intel	⊩
management	Standard Manage	ability on models	with Core i3, Pe	ntium, or Celero	on processo	rs. B
	KVM is supported					
Operating	Microsoft Windows Server 2016/2012 R2/2012, Windows MultiPoint Server 2012, Windows 10 Pro Red Hat Enterprise Linux 6 7/7 2, SUSE Linux Enterprise Server					
systems	Windows 10 Pro. Red Hat Enterprise Linux 6.7/7.2. SUSE Linux Enterprise Server 11/12. VMware vSphere (ESXi) 5.5U3/6.0U2			ll ll		
Page werrenty	11/12. VMware vSphere (ESXI) 5.5U3/6.0U2			6		
Base warranty	,		III 9X3/NDD			
	Supports one of the Ope fixed 250 w		85% 80 PILIS	Bronze qualified	4	L
	<ul> <li>One fixed 250 watts, autosensing, 85%, 80 PLUS Bronze qualified</li> <li>One fixed 400 watts, autosensing, 92%, 80 PLUS Platinum qualified</li> </ul>					
	One lixed 400 W	, ,,				
Power supply	CPU	1		80W		
Power supply	CPU Discrete graphics adapte	er Not su	pported	Sup	pport	
Power supply	CPU	1			port 4 x 3.5" + 1 x 2	2.5"

Components	Specification		
Graphics	Integrated Intel HD Graphics on Xeon E3-12x5 v5, Core i3, Pentium, and Celeron processors. Uses main memory, works along with discrete graphics to support multi-display, enables two display connectors (1 DP, 1 VGA) on rear ports.  Also supports the following discrete graphics adapter options:  NVIDIA Quadro NVS 315, 1GB  NVIDIA Quadro K620, 2GB		
HD Audio	Realtek ALC662 codec		
Front ports	Two USB 3.0		
·	One VGA, one DisplayPort, six USB 3.0, one RJ-45, one serial (9-pin), three analog audio ports (line-in, line-out, mic-in). Optional parallel or serial ports via PCIe adapters		
Noise emissions	Operating: < 35 dB(A). Idle: < 34 dB(A) (Maximum configuration)		
Environmental specification	Temperature - operating	50 °F to 95 °F (10 °C to 35 °C)	
	Temperature - non operating (with package)	-40 °C to 60 °C	
	Altitude - operating	(Unpressurized): 0-10000ft (0-3048m)	
	Humidity - operating	8%~80%, non-condensing	
	Humidity - storage (with package)	10%~90%, non-condensing	



## Disk Bays and PCIe Slots

Disk bays configuration	4 x 3.5"	4 x 2.5"	4 x hybrid 3.5" + 2.5"	
Bay 1	1st HDD bay	1st HDD bay	1st HDD bay, 3.5"/2.5"	
Bay 2	2nd HDD bay	2nd HDD bay	2nd HDD bay, 3.5"/2.5"	
	Not supported	3rd HDD bay	Not supported on standard models. Supports one 2.5" disk drive for special bid only	
	2nd half-height optical, or RDX tape drive, or 3rd HDD bay	2nd half-height optical, or RDX tape drive, or 4th HDD bay	2nd half-height optical, or RDX tape drive, or 3rd HDD bay (3.5"/2.5")	
Bay 5	1st half-height optical, or 9.5mm optical + 4th HDD bay	1st half-height optical, or 9.5mm optical +5th HDD bay	1st half-height optical, or 9.5mm optical + 4th HDD bay (3.5"/2.5")	
6	Four PCIe slots (top-down): Slot 1: PCIe 3.0 x16, full height, half length (near CPU) Slot 2: PCIe 3.0 x1, full height, half length Slot 3: PCIe 3.0 x16 (x4 elec), full height, half length Slot 4: PCIe 3.0 x1, full height, half length			

Model	70LV003FEA
Product	ThinkServer TS150
Region	EMEA
Machine Type	70LV
TopSeller	TopSeller
Processor	Core i3-6320 2C/3.9GHz/4MB/51W/DDR4-2133
Memory	1x8GB UDIMM DDR4-2133 ECC
RAID Controller	RAID 121i
Disk Bays	4x3.5"
Storage	Open
Optical	9.5mm DVD±RW
Add-on NIC	None
Add-on Ports	None
System Management	ISM
Operating System	None
Warranty	1-year
Power Supply	250W 85% Fixed
Ann Date (mm/yy)	10/16